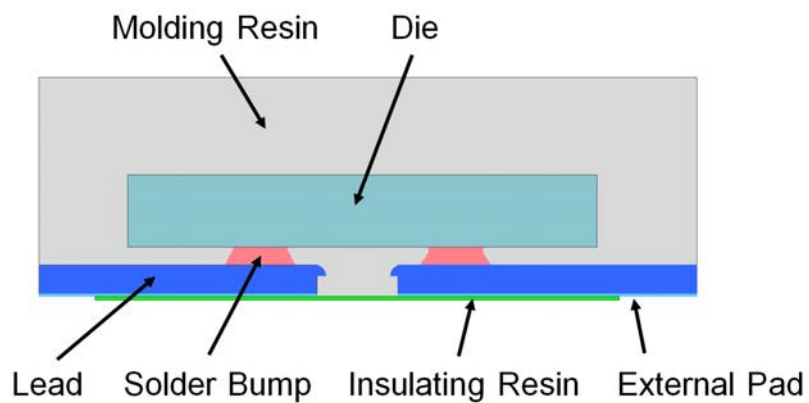


## 1. Package Information

|                    |              |
|--------------------|--------------|
| Package Name       | VMMP16LZ3030 |
| Type               | MMP          |
| Pin Count          | 16           |
| Package Weight [g] | 0.0086       |
| Lead Finish        | Au           |
| MSL                | Level1       |

## 2. Package Structure



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

|                   |       |           |
|-------------------|-------|-----------|
| Packing Form      |       | Tape&Reel |
| Packing Quantity  | [pcs] | 2,500     |
| PIN 1 Orientation |       | E2        |

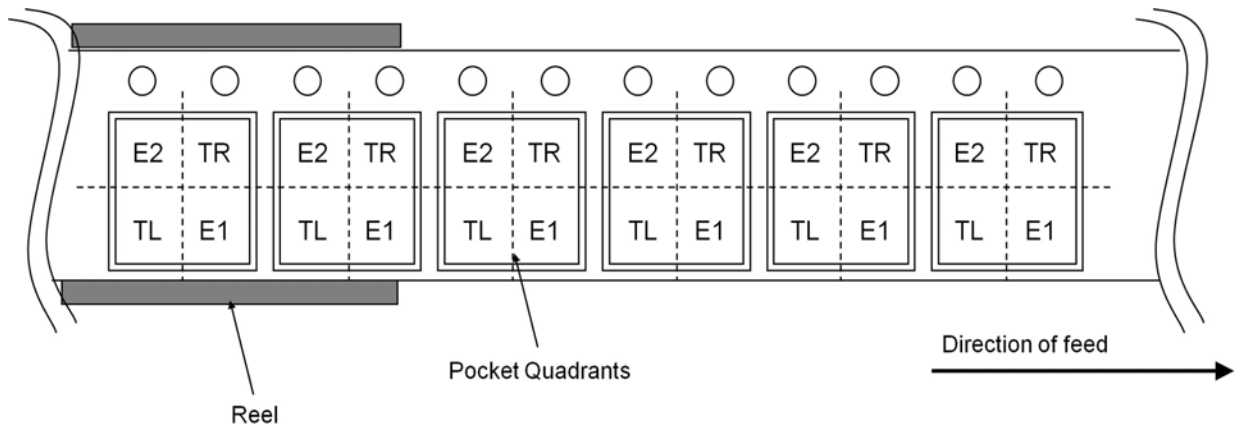


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner.                      TR : PIN1 is placed to the top right corner.  
 TL : PIN1 is placed to the lower left.                              E1 : PIN1 is placed to the lower right.

Fig.1 PIN 1 Orientation in Tape

3.2 Use material

| Item                  | Material  |
|-----------------------|-----------|
| Embossed carrier tape | PS        |
| Cover tape            | PET+PE    |
| Reel                  | PS        |
| Unit box              | Cardboard |
| Shipping box          | Cardboard |

3.3 Leader specification

No component pockets are 1280mm or more.

3.4 Trailer specification

No component pockets are 240 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

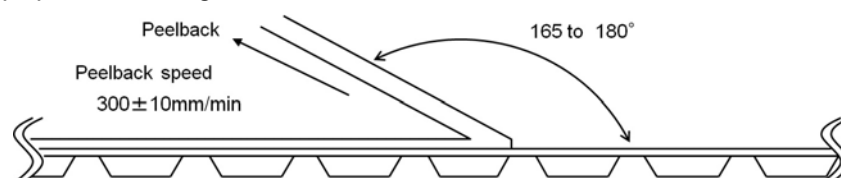


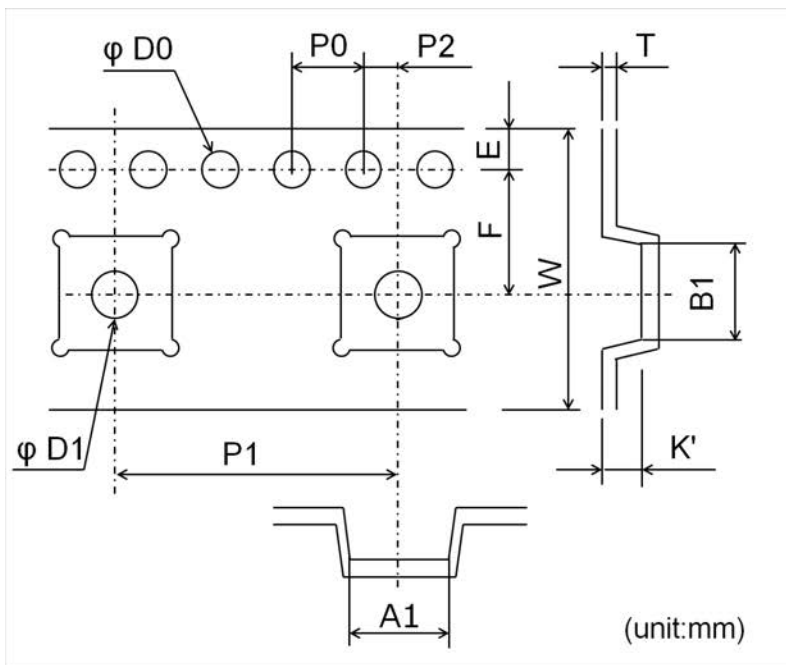
Fig. 2 Test method

3.6 Missing Ics

- (1) No consecutive dropouts.
- (2) A maximum 0.1 % of specified number of products in each packing may be missing.

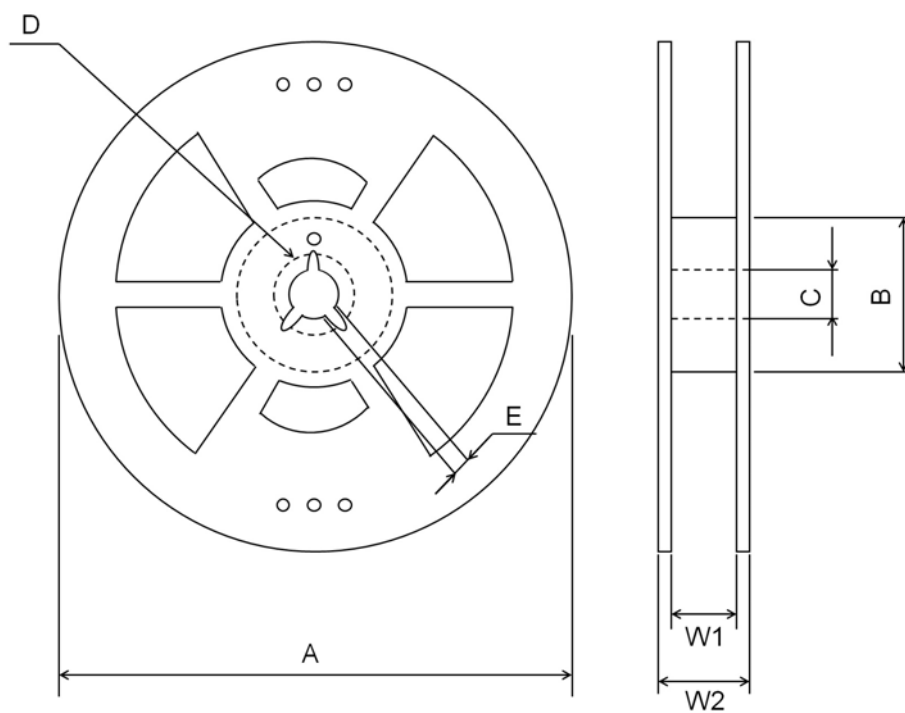
3.7 Tape and Reel Specification

3.7.1 Tape Dimension



|    | Tape Dimension | Tape Tolerance |
|----|----------------|----------------|
| A1 | 3.35           | ±0.1           |
| B1 | 3.35           | ±0.1           |
| D0 | φ1.5           | +0.1/-0        |
| D1 | φ1.05          | +0.1/-0        |
| E  | 1.75           | ±0.1           |
| F  | 5.50           | ±0.05          |
| K' | 0.50           | ±0.05          |
| P0 | 4.00           | ±0.1           |
| P1 | 8.00           | ±0.1           |
| P2 | 2.00           | ±0.05          |
| T  | 0.25           | ±0.05          |
| W  | 8.00           | +0.3/-0.1      |

## 3.7.2 Reel Dimension

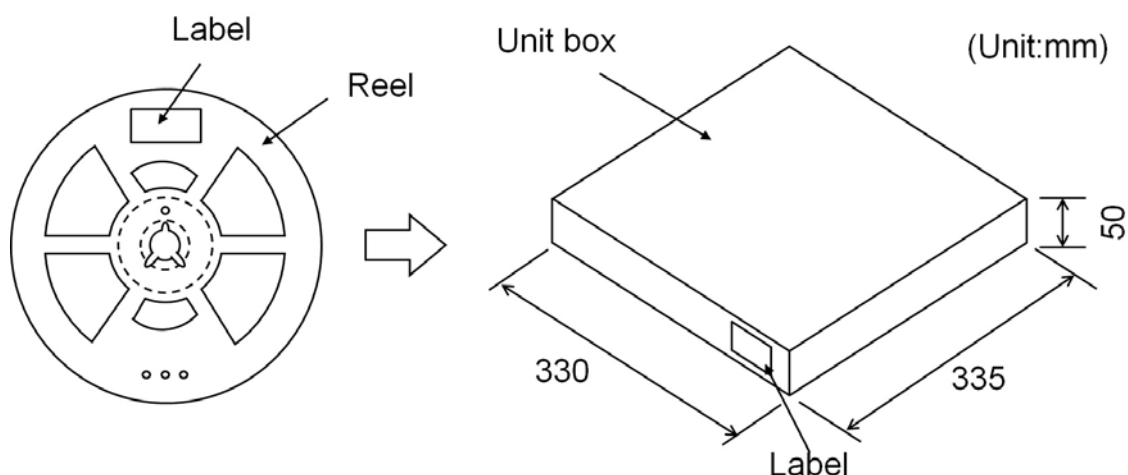


(unit:mm)

|    | Reel Dimension | Reel Tolerance |
|----|----------------|----------------|
| A  | 330            | ±2.0           |
| B  | 80             | ±1.0           |
| C  | 13             | ±0.2           |
| D  | 21             | ±0.8           |
| E  | 2              | ±0.5           |
| W1 | 25.5           | ±1.0           |
| W2 | 29.5           | ±1.0           |

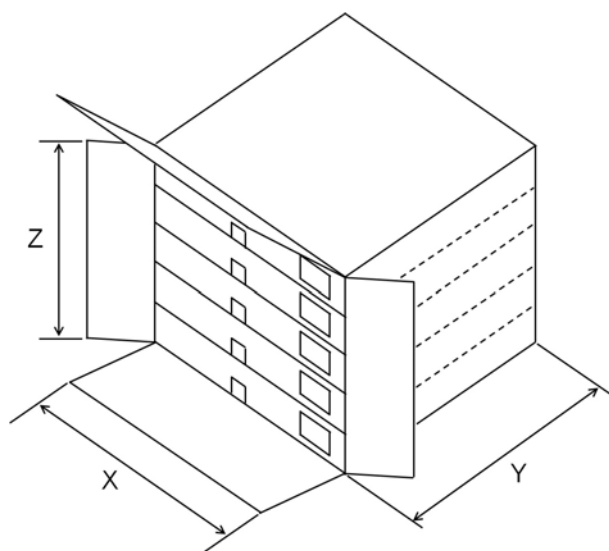
3.8 Packing Method

1 reel(s) or less per unit box



3.9 Packing Style

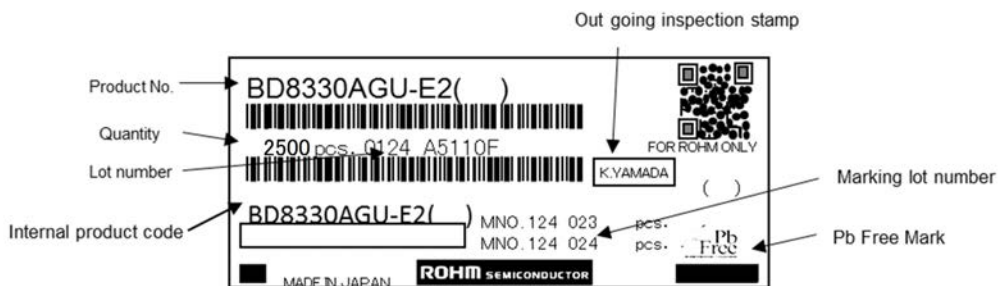
5 unit boxes or less per shipping box



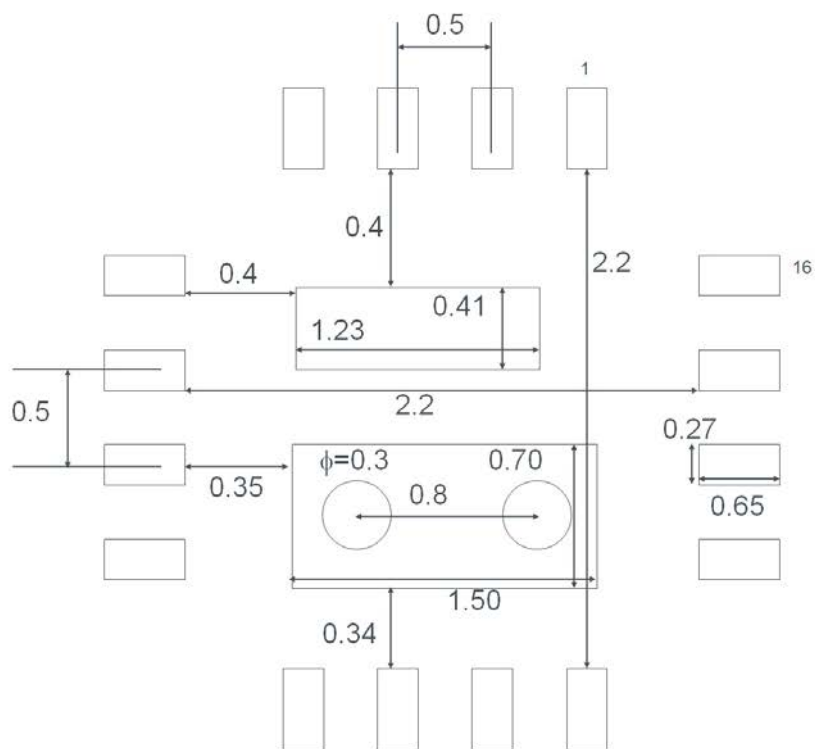
(unit:mm)

| Shipping Box Dimension |     |
|------------------------|-----|
| X                      | 347 |
| Y                      | 353 |
| Z                      | 287 |

3.10 Label Specification



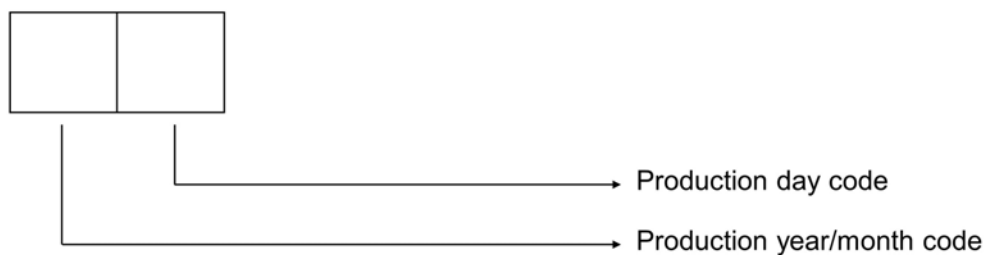
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

## 5. Marking Specification



## 6. Storage conditions

## 6.1 Storage environment

## Recommended storage conditions

|             | Min. | Max. | Unit |
|-------------|------|------|------|
| Temperature | 5    | 30   | °C   |
| Humidity    |      | 85   | % RH |

## 6.2 Storage period (Start to count since delivery date)

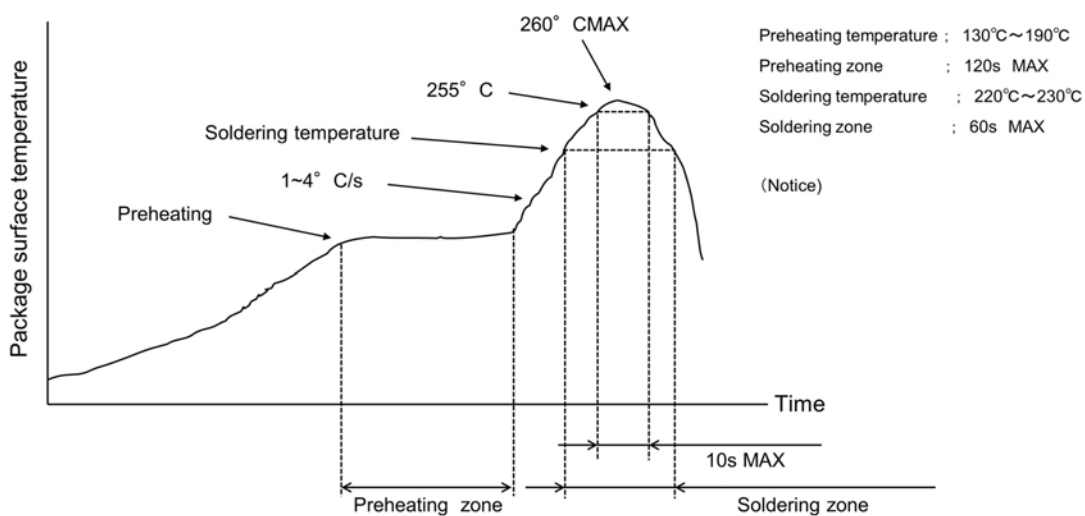
|                | Min. | Max. | Unit |
|----------------|------|------|------|
| Storage period | -    | 1    | year |

## 6.3 Drying process

Dryprocess is not required before solder mounting.

7. Soldering conditions

7.1 Recommended temperature profile for reflow

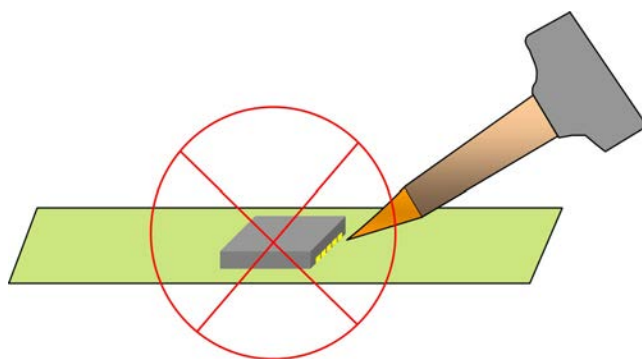


7.2 For wave soldering

The wave soldering method is not supported.

7.3 For solder iron

Rework by soldering iron is not allowed or it may cause mold crack and terminal open.

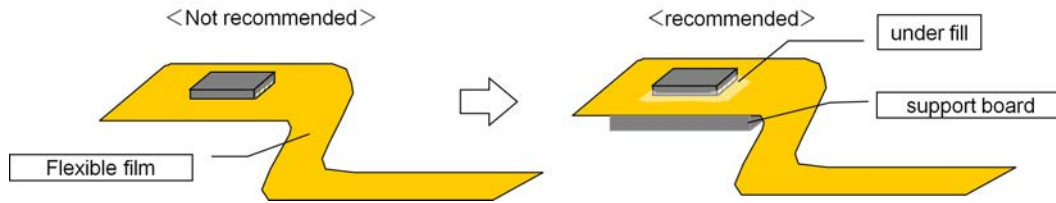




7.4 Caution for solder mounting

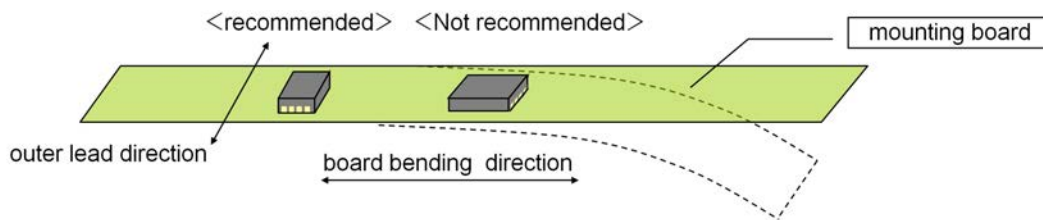
7.4.1 For mounting on flexible film

Mounting on flexible film, film bend may occur lack of lead from package, usage of support board and under fill is recommended.



7.4.2 For Mounting long and narrow board

Mounting on long and narrow board, bending stress may occur a lack of lead from package, bending board direction and outer lead direction is recommended as drawing (vertically layout) and under fill usage is recommended.



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